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Technical Data Sheet Tuffbond® 308

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Product Description

Hernon® Tuffbond® 308 is a specially formulated, low chlorine, single component epoxy system which cures at temperatures of 212°F (100°C) and above. Tuffbond® 308 is suitable for potting and encapsulation of electrical and electronic components. It has excellent storage stability and produces tough, flexible bonds with superior shear strengths when used on metals, ceramics and many plastics. Optimum strength can be obtained after ten to fifteen minutes cure at 300°F (149°C).

Product Benefits

- · Low chlorine content
- · Excellent adhesion
- One part no mixing
- Good mechanical properties
- Tough, flexible bonds
- Suitable for potting electronic boards and encapsulating electrical and electronic components

Typical Properties (Uncured)

Property	Value	
Resin	Ероху	
Color	White	
Viscosity @ 25°C, cP	96,000 to 128,000	
Specific gravity	1.16	
Flash point	See MSDS	

Curing Characteristics

Tuffbond® 308 can be cured by infra-red or convection oven. Cure time will depend on the bondline temperature.

Bondline Temp., °C (°F)	Cure Time, minutes
150 (300)	10 – 15 mins

Typical Properties (Cured)

Property	Value
Heat Resistance, °C (°F)	177 (350)

Typical Cured Performance

Shear Strength, ISO 4587 Cured 10 minutes at 150°C

Substrate	Shear Strength, N/mm² (psi)	
Steel	≥20.6 (≥3000)	
Aluminum	≥17.2 (≥2500)	

Typical Environmental Resistance

Shear Strength, N/mm² (psi), ISO 4587 Abraded epoxy composite, cured 2 hours at 220°F

Humidity Resistance

	8 Days Exposure-Tested at RT		
Control	Room Temperature	160ºF, ~ 85% RH	
≥20.6 (≥3000)	≥20.6 (≥3000)	≥20.6 (≥3000)	

General Information

This product is not recommended for use in pure oxygen and/or oxygen rich systems and should not be selected as a sealant for chlorine or other strong oxidizing materials.

For safe handling information on this product, consult the Material Safety Data Sheet (MSDS).

Storage

Tuffbond[®] **308** must be stored under refrigeration at a temperature of $45 \pm 5^{\circ}$ F for extended shelf life. To prevent contamination of unused material, do not return any material to its original container.

Dispensing Equipment

Hernon[®] offers a complete line of semi and fully automated dispensing equipment. Contact **Hernon**[®] **Sales** for additional information.

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